



TECHNOLOGY & MARKET ANALYST | ADVANCED PACKAGING & MANUFACTURING

With offices in France, Germany, Japan, Greater China and the U.S.A, Yole Développement (Yole) the « More than Moore » company, provides market research, technology analysis, strategic consulting, media services and financial services to a worldwide customer base.

Covering emerging and disruptive silicon and micro manufacturing markets, the group supports companies, investors and R&D organizations by delivering comprehensive analysis that helps them understand the markets and technology trends critical to their business.

JOB DESCRIPTION

Our company proposes a **Technology and Market Analyst** position to help us further develop our **Advanced Packaging & Manufacturing activities** by performing market, technology, and strategic analysis.

You will work in close collaboration within the Advanced Packaging team as well as take part in the projects of the different Divisions (Semiconductor & Software and Photonics & Sensing).

The position would be ideally based in the HQ (France) but remote is possible.

Regular business trips (Europe, USA, Asia) are expected.

RESPONSABILITIES

As an Advanced Packaging Analyst, you will be responsible to :

- Execute technical, marketing, and strategic analysis
- Oversee technology and industry insights from Advanced Packaging and Manufacturing market trends, from devices to package type (3D, fan-out, flip chip, embedded die...)
- Understand the impact of the emergence of new or improved technologies in various applications
- Execute projects within a given timeframe and budget.
- Participate in the establishment and structuration of commercial offers
- Create and manage long-term relationships with customers
- Collect information and promote our activities in conferences and dedicated trade-shows
- Give presentations at international conferences and workshops.

EDUCATION / EXPERIENCE

- Experience (3-5 years) in the semiconductor and possibly in the advanced packaging field
- Good knowledge of the Advanced Packaging technologies : 3D, System In Package, flip chip, fan out, waferlevel-packaging as well as advanced substrate
- University Degree (Master, Engineer, PhD) in a semiconductor-related field is mandatory (Materials Science, Microelectronics, Electronics or equivalent.)
- Strong interest in product market entry / applications (marketing, strategic planning, etc.)
- Required English level: minimum CECR - CI / TOEIC 900

Please send your latest CV & cover letter to recruiting@yole.fr

